

covering Electronic Components,
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Approval Independent Testing Laboratory

IECQ Certificate No.: IECQ-L JQAJP 13.0002

CB Certificate No.: JQAQ0002-001-T

Schedule Number: IECQ-L JQAJP 13.0002-S Rev No.: 5 Revision Date: 2016/12/22 Page 1 of 8

TESTD PARTS

Fixed capacitor, Fixed resistor, Potentiometer, Varistor, Thermistor, Connector, Relay, Switch, Printed circuit board, Semiconductor Devices, Semiconductor Integrated Circuit and Optical Component

ENVIRONMENTAL TEST

IEC 60068-2-1:2013	Cold
IEC 60068-2-2:2007	Dry heat
IEC 60068-2-11:1981	Salt mist
IEC 60068-2-14:2009	Change of temperature
IEC 60068-2-20:2008	Test methods for solderability and resistance
	to soldering heat of devices with leads
IEC 60068-2-30:2005	Damp heat, cyclic (12+12-hour cycle)
IEC 60068-2-38:2009	Composite temperature/humidity cyclic test
JIS C 60068-2-42:1993	Sulphur dioxide test for contacts and connections
JIS C 60068-2-43:1993	Hydrogen sulphide test for contacts and connections
IEC 60068-2-45:1980	Immersion in cleaning solvents
IEC 60068-2-52:1996	Salt mist, cyclic (sodium chloride solution)
IEC 60068-2-54:2006	Soldering. Solderability testing by
	the wetting balance method
IEC 60068-2-58:2004	Test methods for solderability, resistance to dissolution of
	metallization and to soldering heat of SMD
IEC 60068-2-60:1995	Flowing mixed gas corrosion test
IEC 60068-2-66:1994	Damp heat, steady state (unsaturated pressurized vapour)
IEC 60068-2-78:2012	Damp heat, steady state
MIL STD 202G	Test method standard electronic and electrical component parts
MIL STD 883J	Test method standard microcircuts





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MECHANICAL TEST

IEC 60068-2-6:2007 Vibration (sinusoidal)

Robustness of terminations and IEC 60068-2-21:2006

integral mounting devices

IEC 60068-2-27:2008

IEC 60068-2-31:2008 Rough handling shocks, primarily for

equipment-type specimens

Tests and Guidance: Combined climatic (temperature/humidity) IEC 60068-2-53:2010

and dynamic (vibration/shock) tests

STRESS TEST

JEITA ED-4701/302:2013

Environmental and endurance test methods for semiconductor devices (Stress test I-2)

Test method 304A Human body model electrostatic discharge (HBM/ESD) Test method 305C Charged device model electrostatic discharge (CDM/ESD)

Test method 306B Latch-up

JEITA ED-4701/600:2013

Environmental and endurance test methods for semiconductor devices

(Specific test for discrete semiconductors)

Test method 601 Power cycling test (Molding type)

Test method 602 Power cycling test (Non-molding type/short time) Test method 603

Power cycling test (Non-molding type/long time)





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LED OPTICAL CHARACTERISTIC TEST

JIS C 7801:2009

Measuring methods of lamps for general lighting

JIS C 8152-1:2012

Photometry of white light emitting diode for

general lighting — Part 1: LED packages

JIS C 8152-2:2012

Photometry of white light emitting diode for general lighting

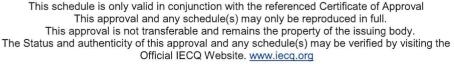
- Part 2: LED modules and LED light engines

JIS C 8105-5:2011

Luminaires — Part 5: Gonio-photometric method

OTHER TEST

Failure Analysis, Construction Analysis, Elemental Analysis, Thermal Analysis and Internal Gas Analysis of Electronic component, including Electrical Analysis, NDE (Non-destructive Engineering), PhysicalAnalysis, Chemical Analysis and Sample Preparation (Decap, X-section, etc),







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MEASUREMENT RANGE

Passive component

Type / Part name	Measurable property value M	leasuring range
Fixed capacitor	(1)Voltage endurance (DC)	: AC,DC 0 ~ 5kV
	(2)Insulation resistance	$5 \times 10^5 \Omega \sim 10^{14} \Omega$
	(3)leakage current	$1 \times 10^{-3} \sim 10 \text{ A}^{-11}$
	(4)Capacitance	: $18pF \sim 1F^*$
	(5)Dielectric loss tangent(D factor)	: 10* min
	(6)Impedanc	$: 1\Omega \sim 10^* M\Omega$
	(7)Temperature properties and	
	gap of the capacitance.	: Temperature range $-40^{\circ}\text{C} \sim +150^{\circ}\text{C}$
	Attention: * The mark varies	s according to measurement frequency.
	(1)Resistance value	$:1 \Omega \sim 100 M\Omega$
	(2)Resistance temperature properties and	
Fixed resistor	gap of the resistance level.	:Temperature range -55° C $\sim +150^{\circ}$ C
Fixed resistor	(3)Voltage factor	:±0.02%/V
	(4)Insulation resistance	: $5 \times 10^5 \Omega \sim 2 \times 0^{14} \Omega$
	(5)Voltage endurance	: AC,DC $0 \sim 5 \text{kV}$
	(1)Resistance value	: $1 \Omega \sim 100 \text{M}\Omega$
	(2)Mutual deviations	: ±3%
	(3)Resistance temperature properties and	I
Variable resistor	gap of the resistance level.	:Temperature range -40° C $\sim +150^{\circ}$ C
*potentiometer	(4)Insulation resistance	$: 5 \times 10^5 \Omega \sim 10^{14} \Omega$
	(5) Voltage endurance	: AC,DC $0 \sim 5 \text{kV}$
	(6)Rotational noise	:Noise voltage 1mV
	(7)Intensive contact resistance	:1 mΩ
Varistor	Voltage at reference current	:1500V(1mA min)
Thermistor	(1)resistance value	$:1\Omega \sim 1000 k\Omega$
	(2)The thermistor fixed number	:Temperature range -50° C $\sim +300^{\circ}$ C





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MEASUREMENT RANGE

Active component part [Individual semiconductor part]

Type / Part name	Measurable property value M	leasuring range
· ·	(1)Collector-base breakdown voltage	:1V ~ 1.5kV
	(2)Collector-emitter breakdown voltage	:1V ~ 1.5kV
	(3)Emitter base breakdown voltage	:100V min
Transistor	(4)Collector base interception electric curr	rent $:1nA \sim 100mA$
*Bipolar	(5)Collector emitter interception electric of	current $:1nA \sim 100mA$
_	(6)Emitter base interception electric curre	nt :1nA ~ 100mA
	(7)The collector emitter saturation voltage	$e:7V \min (I_C < 17A)$
	(8)DC current gain	$:25 \sim 25,000 \; (I_C < 17A)$
	(1)Gate source breakdown voltage	:1V ~ 1.5kV
Transistor	(2)Gate leak electric current	$:1pA \sim 100mA$
*Field effect form	(3)Drain current	:1nA ~ 1A
Fleid effect form	(4)The gate cut-off voltage	: ~ 100V
	(5)The drain source saturation voltage	:7V min $(I_D < 17A)$
Diode	(1)Forward voltage	:7V min $(I_F < 17A)$
*Small signal	(2)Reverse current	$:1 \text{na} \sim 100 \text{mA} (V_R < 100 \text{V})$
*I rectify a small electric current	(3)Breakdown voltage	:1V ~ 1.5kV
*Constant voltage	(4)Zener voltage	:100V min
*Small electric current switching	(5)Dynamic resistance	:50 Ω max
	(6)Temperature coefficient	:Temperature range -55° C $\sim +150^{\circ}$ C
Thyristor	(1)Off electric current	$:1 \mathrm{mA}(\mathrm{V_L} < 1 \mathrm{kV})$
*3 reverse-blocking terminals	(2)Reverse current	$:1 \text{na} \sim 1 \text{mA} \left(V_L \leq 1 \text{kV}\right)$
*Small electric current	(3)ON-state voltage	$: 7V (I_{TM} < 10A)$
	(4)Gate trigger	:1000V min
	(5)Holding current	$:10A(V_{TM} < 7V)$





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MEASUREMENT RANGE

Active component part Semicondctor Devices [Integrated circuit]

Type / Part name	Measurable property value Mea	suring range
	(1)The high-level output voltage	:±30V
	(2)The low-level output voltage	:±30V
	(3)The input clamp voltage	:±30V
TTL IC	(4)High-level input electric current	:±300mA
TILIC	(5)Low-level input electric current	:±300mA
	(6)Output short circuit current	:±300mA
	(7) High-level power supply electric current	:±300mA
	(8)Low-level power supply electric current	:±300mA
	(1)The high-level output voltage	:±30V
	(2)The low-level output voltage	:±30V
	(3)The high-level input voltage	:±20V
CMOS IC	(4)Low-level input electric current	:±20V
CMOS IC	(5)High-level output electric current	:±300mA
	(6)Low-level output electric current	:±300mA
	(7)Static consumption electric current	:±300mA
	(8)Input current	:±300mA
	(1)Input-offset voltage	$:\!10\mu V\sim 128mV$
	(2)Input offset current	:20pA ~ 16μA
	(3)Input bias current	:20pA ~ 16μA
Analog comiconductor integrated	(4)Open loop voltage gain	$: 0.1 V/mV \sim 1.2 V/\mu V$
Analog semiconductor integrated circuit *Monolithic op-amp	(5)The max power voltage	$:10 \text{mV} \sim 50 \text{V}$
	(6)Power consumption	$:5 \text{mW} \sim 6.4 \text{W}$
	(7)Common mode rejection ratio	:38 ~ 116dB
	(8)Supply voltage rejection ratio	:38 ~ 116dB
	(9)Aspect input voltage range	$:100 \text{mV} \sim 25 \text{V}$
	(10)Slew rate	$:0.1 \sim 125 V/\mu S$





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MEASUREMENT RANGE

Mechanical device

Type / Part name	Measurable property value	Measuring range
Connector (Electronic equipment use)	(1)Insulationresistanc	$:5\times 10^5\Omega \sim 2\times 10^{14}\Omega$
	(2)Withstand voltage	:AC,DC $0 \sim 5 \text{kV}$
	(3)Contact resistance under low voltage,	
	the low electric current	$1 \text{m}\Omega \sim 100\Omega$
	(4)Chattering of the contact.	:1µsec max
	(1)Withstand voltage	:AC,DC $0 \sim 5 \text{kV}$
	(2)Insulation resistance	$:5\times 10^5\Omega \sim 2\times 10^{14}\Omega$
	(3)Direct current resistance of the coil	$:1\Omega \sim 10$ k Ω
	(4)Contact resistance	$1 \text{m}\Omega \sim 100\Omega$
Relay	(5)Operating voltage	:1V max
(Small form for control)	(6)Must-release voltage	:1V max
	(7)Operation time	:1msec max
	(8)Recovery time	:1msec max
	(9)Bounces of the point of contact	:1μsec max
	(10)Chattering of the point of contact	:1μsec max
Switch (Electronic equipment use)	(1)Contact resistance	$1 \text{m}\Omega \sim 100\Omega$
	(2)Insulation resistance	$:5\times10^5\Omega\sim2\times10^{14}\Omega$
	(3)Withstand voltage	: AC,DC $0 \sim 5$ kV
	(4)Electrostatic capacity	$:18pF \sim 1F$
	(5)Change of the contact resistance	$:1 \text{m}\Omega \text{ max}$
Printed circuit board	(1)Resistance of the plating part of	
	the conductor and through hall p	art. : $1 \text{m}\Omega \sim 1000\Omega$
	(2)Withstand voltage	: AC,DC $0 \sim 5$ kV
	(3)Insulation resistance	$: 5 \times 10^5 \Omega \sim 10^{14} \Omega$





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MEASUREMENT RANGE

Optical component

Type / Part name	Measurable property value	Measuring range	
Luminescent diode (It is for indication.)	(1)Forward voltage	:7V min	
	(2)Reverse current	:1mA min	
	(3)Luminous intensity(Relative v	alue) :	
	1.Integrating sphere		
	(1)Total luminous flux[lm]	:Measurable wavelength range	
		350nm ~ 1000nm	
		:F[lm] :min 32lm ~ In sunshine	
	(2)Color temperature[K]	[
	(3)Chromaticity coordinate	:	
	(4) The number of the color rendering evaluations :Ra,R1 ~ R14		
	2.The light distribution measurement.		
LED	(1)Light distribution curve	:Measurable wavelength range	
(It is for illumination.)		360nm ~ 830nm	
		:Photometric distance 2m ~ 12m,	
	(2)Light intensity(Reference)	•	
		$(2.0 \text{m} : 9 \sim 3,680,000[\text{cd}])$	
		$:3.0m:$ $20 \sim 8,200,000[cd]$	
		:6.0m : $83 \sim 33,000,000$ [cd]	
		:12m : $330 \sim 132,000,000[cd]$	
	(3)Color temperature	:	
	(4)Chromaticity coordinate	:	
	(5)The number of the color re	endering evaluations: Ra,R1 ~ R14	

